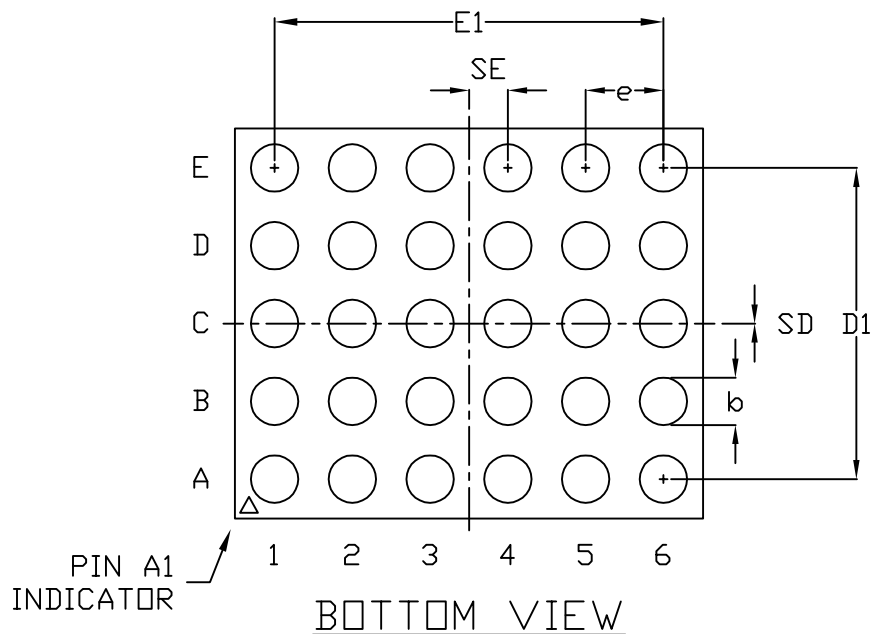


TOP VIEW



BOTTOM VIEW



SIDE VIEW

COMMON DIMENSIONS	
A	0.62+0.05-0.08
A1	0.29±0.02
A2	0.33 REF.
b	∅0.35±0.03
D	2.55±0.10
D1	2.00 BASIC
E	3.06±0.10
E1	2.50 BASIC
e	0.50 BASIC
SD	0.00 BASIC
SE	0.25 BASIC

PKG. CODE	DEPOPULATED SOLDER BALLS
B30-1	NONE
B30-2	B4, C1, C4, D4
B30-3	B2, B3, B4 C2, C3, C4 D2, D3, D4, D5
B30-4	B3, B4 C2, C3, C4, C5 D3, D4

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED.
2. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC #10-0131.
3. PRODUCT MARKING: NUMBER OF CHARACTERS AND LINES VARY PER PRODUCT
4. ALL DIMENSIONS APPLY BOTH TO LEAD FREE (+) & LEADED (-) PKG. CODES.
5. PACKAGE CODE: B30-1, B30-2
B30-3, B30-4



TITLE:
PACKAGE OUTLINE, 30 BUMPS, UCSP,
2.55x3.06x.062mm, 0.5mm PITCH

APPROVAL	DOCUMENT CONTROL NO. 21-0123	REV. H	1/1
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-DRAWING NOT TO SCALE-